

Quik-Pak Exhibits Air Cavity Plastic QFNs, Overmolded QFNs at IEEE MTT International Microwave Symposium (IMS) June 4-9, Honolulu HI, Booth 732

San Diego, CA – PR Newswire June 1, 2017 – [Quik-Pak](#), a provider of innovative microelectronic packaging and assembly solutions for complex devices, will exhibit [Air Cavity Plastic QFN Packages](#) and [Overmolded QFN Packages](#) in Booth 732 at the IEEE MTT International Microwave Symposium (IMS), June 4-9, 2017 in Honolulu, HI.

- Quik-Pak's [air cavity plastic QFN packages](#), also known as Open-molded Plastic Packages (OmPP), are used in RF/microwave, MEMS and sensor applications. OmPPs feature gold plating for wire bondability; RoHS- and REACH-compliant green molding compound; short, highly conductive interconnects and JEDEC outlines. Matching ceramic, plastic, quartz or glass lids with b-stage epoxy seals are available. More than 30 off-the-shelf sizes are in stock for prototype, mid-volume and production-volume requirements. Custom designs are also available. More details can be found in Quik-Pak's [product brochure](#)
- Quik-Pak's [overmolded, open-tooled QFN packages](#) are well suited for quick-turn engineering builds, high mix/low volume assembly and onshore volume production. The QFNs are available for purchase off the shelf in over 35 designs, from 2x2 mm to 12x12 mm, with multiple thicknesses. Five-day delivery of assembled QFNs is standard. All QFNs are RoHS compliant and utilize NiPdAu-plated lead frames. Custom designs are also available with quick lead-times.

“Our versatile, cost-effective QFN platform has become the package of choice for single die, multi-die, SiPs and stacked die,” said Quik-Pak Global Sales and Marketing Director Casey Krawiec. “We look forward to discussing device packaging for RF/microwave applications with IMS attendees. Our QFNs offer great convenience to everyone who uses them. They will help you get your die to market faster.”

Quik-Pak also offers complete assembly services to help accelerate time to market, including flip chip and wire bonding (Au, Al and Cu from 0.6 mil to 20 mil diameters), wafer thinning, dicing, and pick and place.

The [IEEE MTT International Microwave Symposium \(IMS\)](#) is the premier annual international meeting for technologists involved in all aspects of microwave theory and practice. More than 400 companies will exhibit the latest developments in packaging, materials, devices, components and subsystems, as well as design and simulation software and test/measurement equipment.

Quik-Pak, a division of [Promex](#), provides IC packaging, assembly and wafer preparation services in its ISO 9001:2008 certified, ITAR registered facility in San Diego, California. The company's overmolded QFN/DFN packages and pre-molded air cavity QFN packages provide a fast, convenient solution for prototype to full production needs. Same-day assembly services are provided to reduce time to market. More information is available at <http://www.icproto.com> or by calling 858-674-4676.

Photos #1 & 2 caption:

Quik-Pak's [air cavity plastic QFN packages](#) for RF/microwave, MEMS and sensor applications and [overmolded QFN packages](#) for quick-turn engineering builds, high mix/low volume assembly and onshore volume production are available in over 35 off-the-shelf designs.

Photo #1

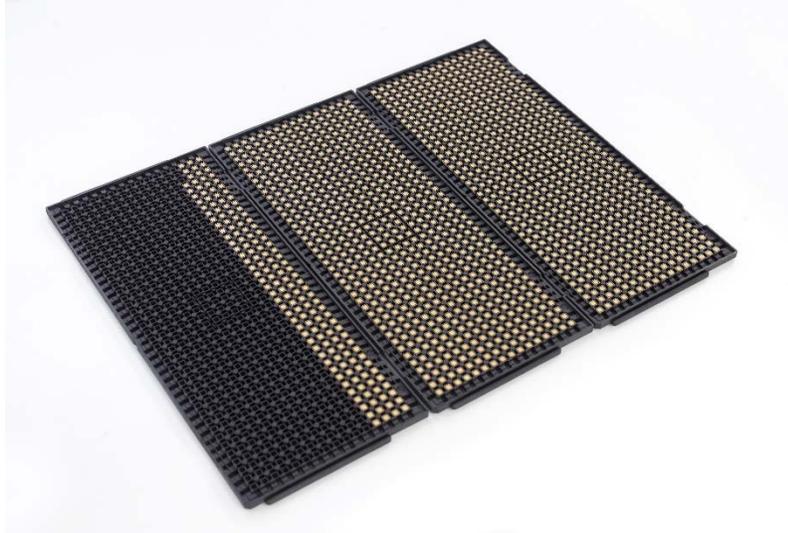


Photo #2

